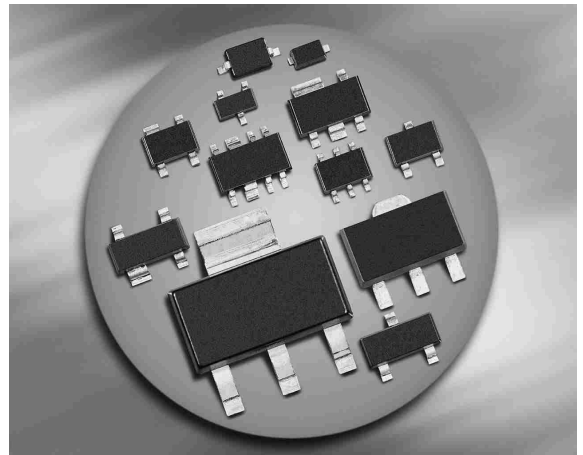
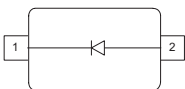


Silicon Schottky Diode

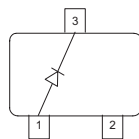
- General-purpose diode for high-speed switching
- Circuit protection
- Voltage clamping
- High-level detecting and mixing
- BAS70-04S: For orientation in reel see package information below
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101¹⁾



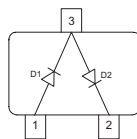
BAS170W
BAS70-02L
BAS70-02W
BAS70-02V



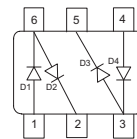
BAS70



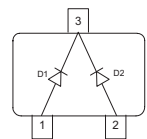
BAS70-04
BAS70-04W



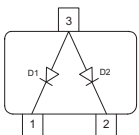
BAS70-04S



BAS70-05
BAS70-05W



BAS70-06
BAS70-06W



BAS70-07
BAS70-07W



¹⁾BAS70-02L is not qualified according AEC Q101

Type	Package	Configuration	L_S (nH)	Marking
BAS170W	SOD323	single	1.8	white 7
BAS70	SOT23	single	1.8	73s
BAS70-02L	TSLP-2-1	single, leadless	0.4	F
BAS70-02V	SC79	single	0.6	c
BAS70-02W*	SCD80	single	0.6	73
BAS70-04	SOT23	series	1.8	74s
BAS70-04S	SOT363	dual series	1.6	74s
BAS70-04W	SOT323	series	1.4	74s
BAS70-05	SOT23	common cathode	1.8	75s
BAS70-05W	SOT323	common cathode	1.4	75s
BAS70-06	SOT23	common anode	1.8	76s
BAS70-06W	SOT323	common anode	1.4	76s
BAS70-07	SOT143	parallel pair	2	77s
BAS70-07W	SOT343	parallel pair	1.8	77s

* Not for new design

Maximum Ratings at $T_A = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	70	V
Forward current	I_F	70	mA
Non-repetitive peak surge forward current $t \leq 10\text{ms}$	I_{FSM}	100	
Total power dissipation	P_{tot}		mW
BAS70, BAS70-07, $T_S \leq 72\text{ °C}$		250	
BAS70-02L, $T_S \leq 117\text{ °C}$		250	
BAS70-02W, -02V, $T_S \leq 107\text{ °C}$		250	
BAS70-04, BAS70-06, $T_S \leq 48\text{ °C}$		250	
BAS70-04S/W/-06W, BAS170W, $T_S \leq 97\text{ °C}$		250	
BAS70-05, $T_S \leq 22\text{ °C}$		250	
BAS70-05W, $T_S \leq 90\text{ °C}$		250	
BAS70-07W, $T_S \leq 114\text{ °C}$		250	
Junction temperature	T_J	150	°C
Operating temperature range	T_{op}	-55 ... 125	
Storage temperature	T_{Stg}	-55 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}		K/W
BAS70, BAS70-07		≤ 310	
BAS70-02L		≤ 130	
BAS70-02W, -02V		≤ 170	
BAS70-04, BAS70-06		≤ 410	
BAS70-04S/W, BAS70-06W		≤ 210	
BAS70-05		≤ 510	
BAS70-05W		≤ 240	
BAS70-07W		≤ 145	
BAS170W		≤ 190	

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

DC Characteristics

Breakdown voltage $I_{(BR)} = 10\ \mu\text{A}$	$V_{(BR)}$	70	-	-	V
Reverse current $V_R = 50\ \text{V}$	I_R	-	-	0.1	μA
Forward voltage $I_F = 1\ \text{mA}$ $I_F = 10\ \text{mA}$ $I_F = 15\ \text{mA}$	V_F	300 600 720	375 705 880	410 750 1000	mV
Forward voltage matching ²⁾ $I_F = 10\ \text{mA}$	ΔV_F	-	-	20	

¹⁾For calculation of R_{thJA} please refer to Application Note AN077 (Thermal Resistance Calculation)

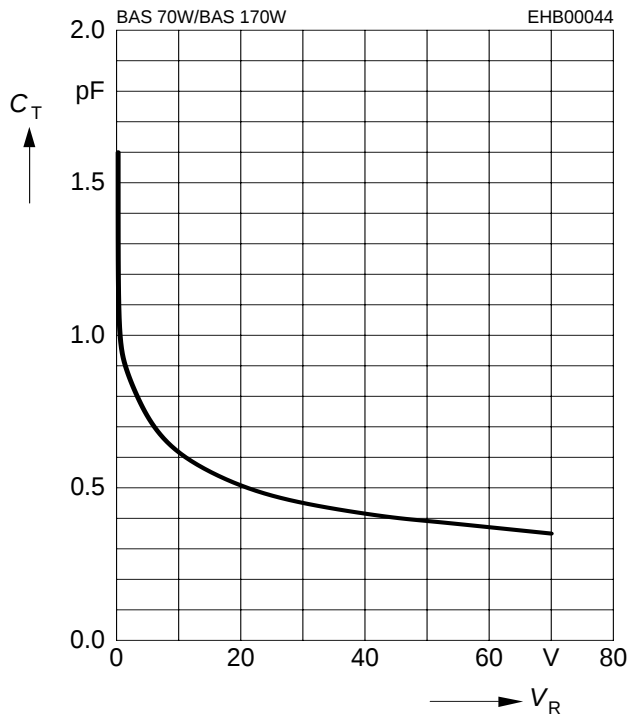
²⁾ ΔV_F is the difference between lowest and highest V_F in a multiple diode component.

Electrical Characteristics at $T_A = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics					
Diode capacitance $V_R = 0$, $f = 1\text{ MHz}$	C_T	-	1.5	2	pF
Forward resistance $I_F = 10\text{ mA}$, $f = 10\text{ kHz}$	r_f	-	34	-	Ω
Charge carrier life time $I_F = 25\text{ mA}$	τ_{rr}	-	-	100	ps

Diode capacitance $C_T = f(V_R)$

$f = 1\text{ MHz}$



Forward resistance $r_f = f(I_F)$

$f = 10\text{ kHz}$



Reverse current $I_R = f(V_R)$

$T_A = \text{Parameter}$



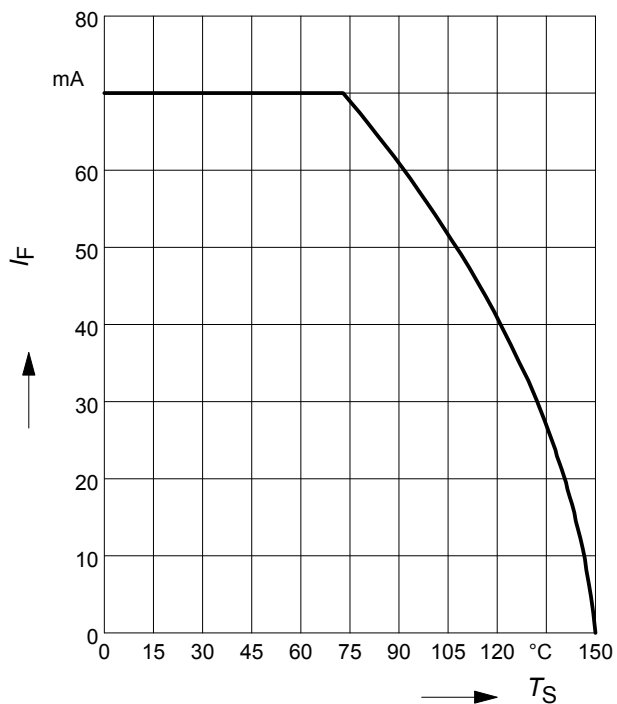
Forward current $I_F = f(V_F)$

$T_A = \text{Parameter}$



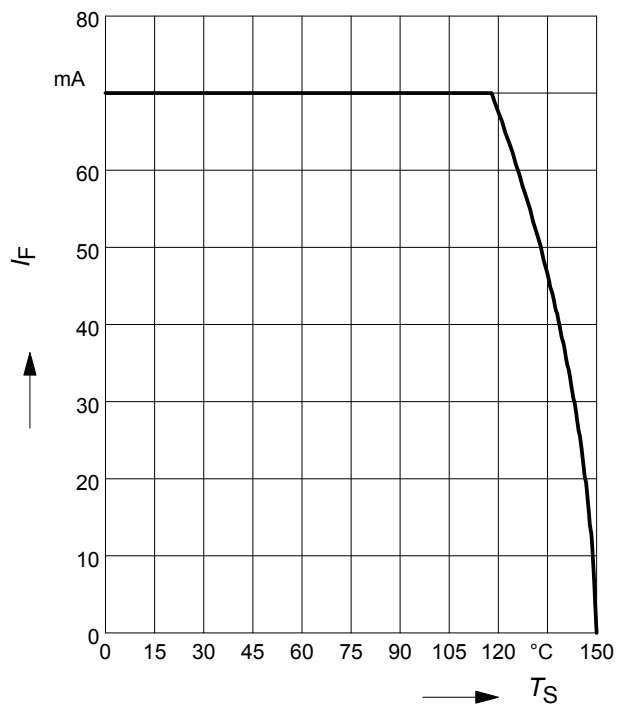
Forward current $I_F = f(T_S)$

BAS70, BAS70-07



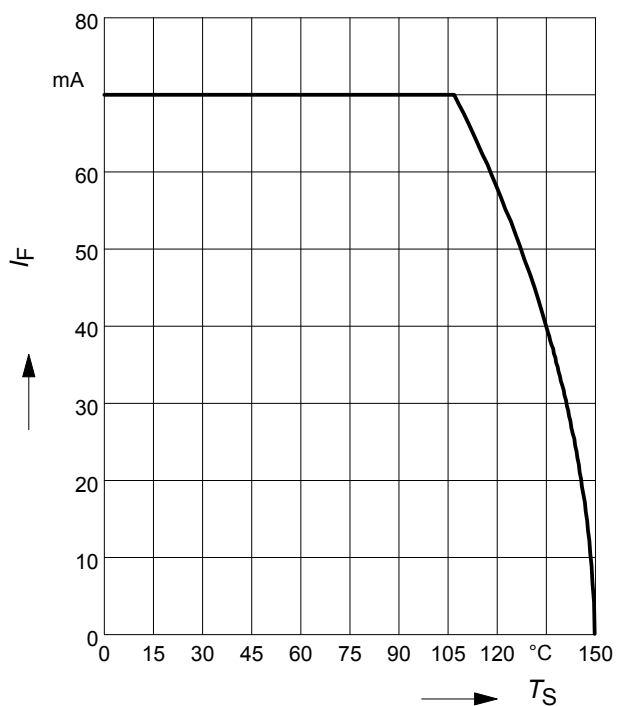
Forward current $I_F = f(T_S)$

BAS70-02L



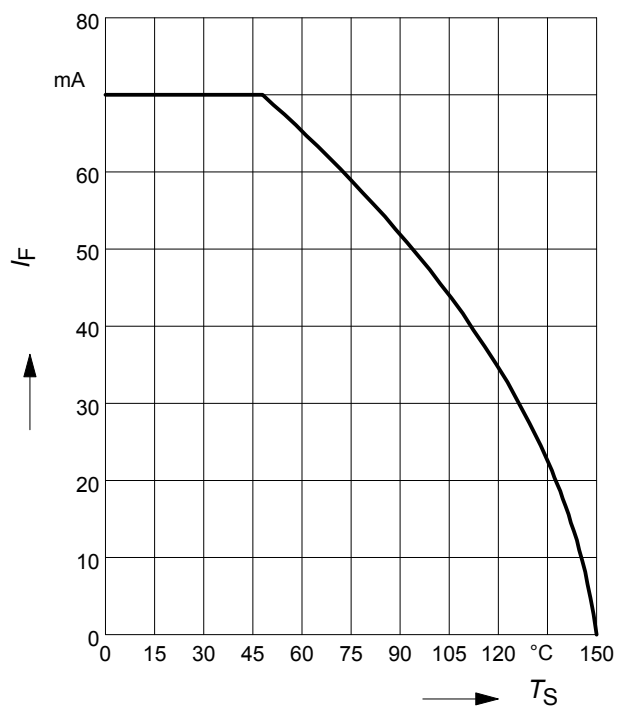
Forward current $I_F = f(T_S)$

BAS70-02W, -02V



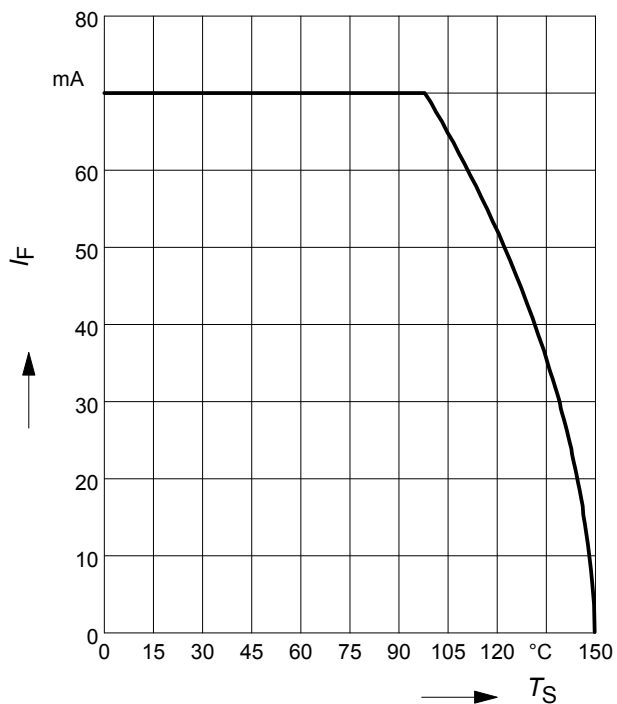
Forward current $I_F = f(T_S)$

BAS70-04, BAS70-06



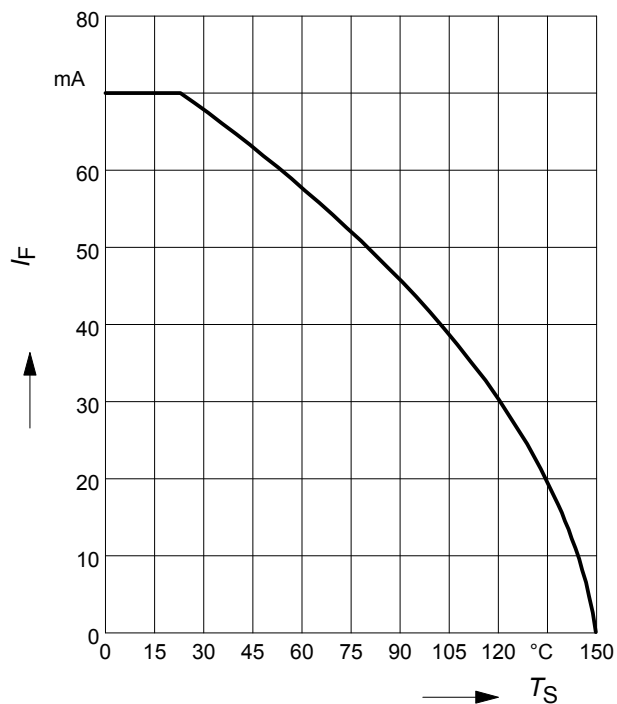
Forward current $I_F = f(T_S)$

BAS70-04S/W, BAS70-06W, BAS170W



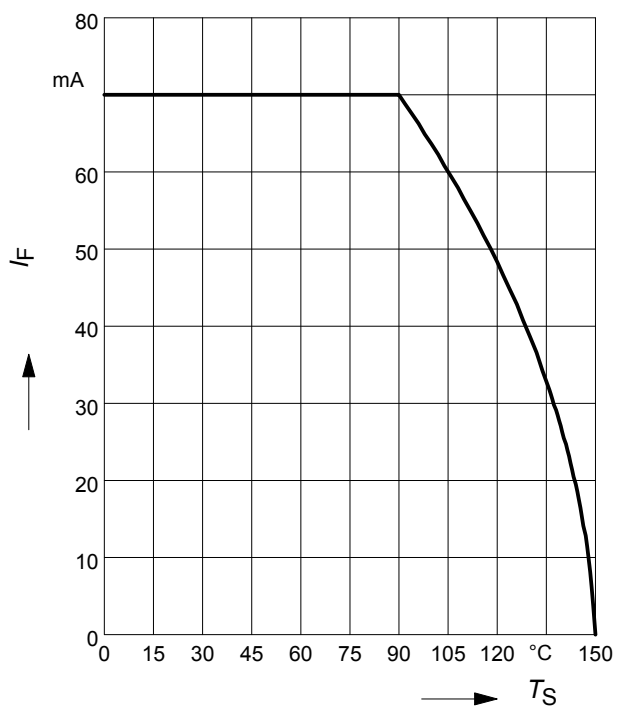
Forward current $I_F = f(T_S)$

BAS70-05



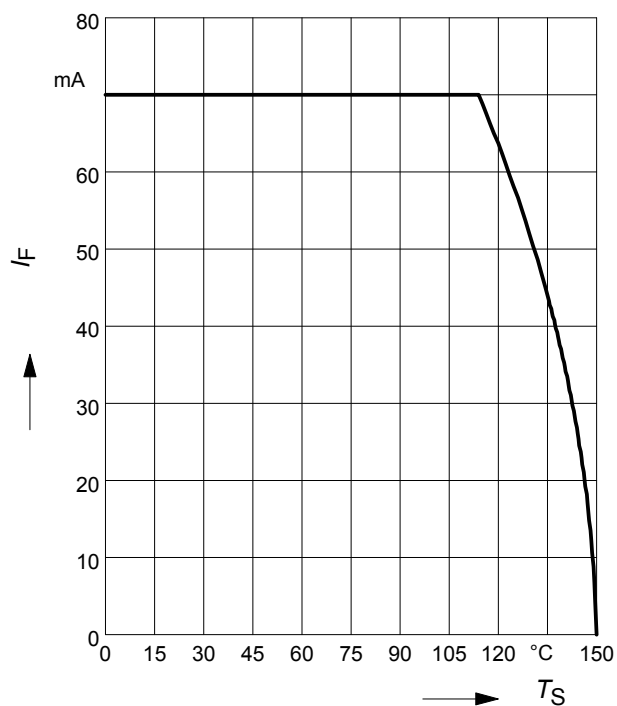
Forward current $I_F = f(T_S)$

BAS70-05W



Forward current $I_F = f(T_S)$

BAS70-07W



Forward current $I_F = f(T_S)$

BAS170W



Permissible Puls Load $R_{thJS} = f(t_p)$

BAS70



Permissible Pulse Load

$I_{Fmax}/I_{FDC} = f(t_p)$

BAS70



Permissible Puls Load $R_{thJS} = f(t_p)$

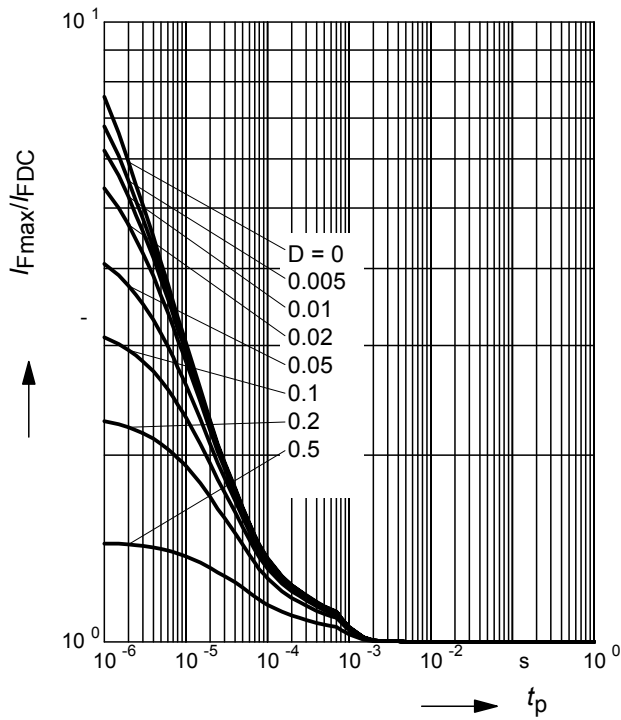
BAS70-02L



Permissible Pulse Load

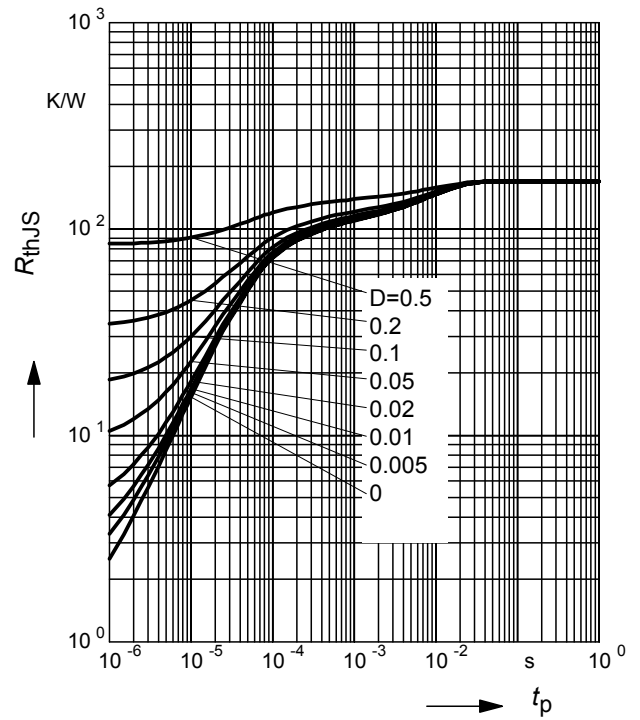
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAS70-02L



Permissible Puls Load $R_{thJS} = f(t_p)$

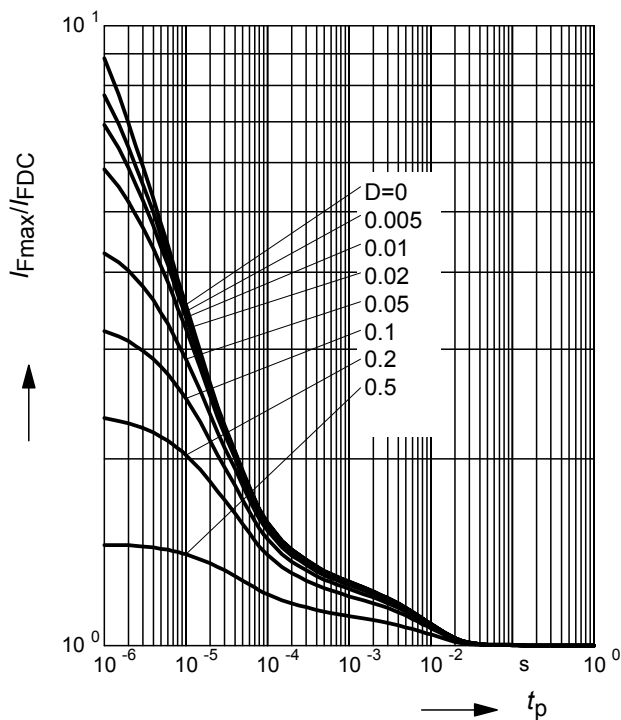
BAS70-02W, -02V



Permissible Pulse Load

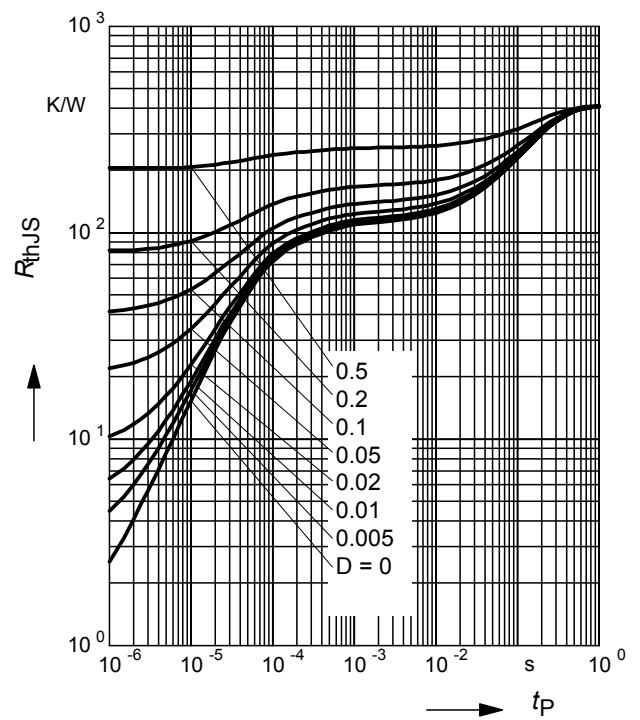
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAS70-02W, -02V



Permissible Puls Load $R_{thJS} = f(t_p)$

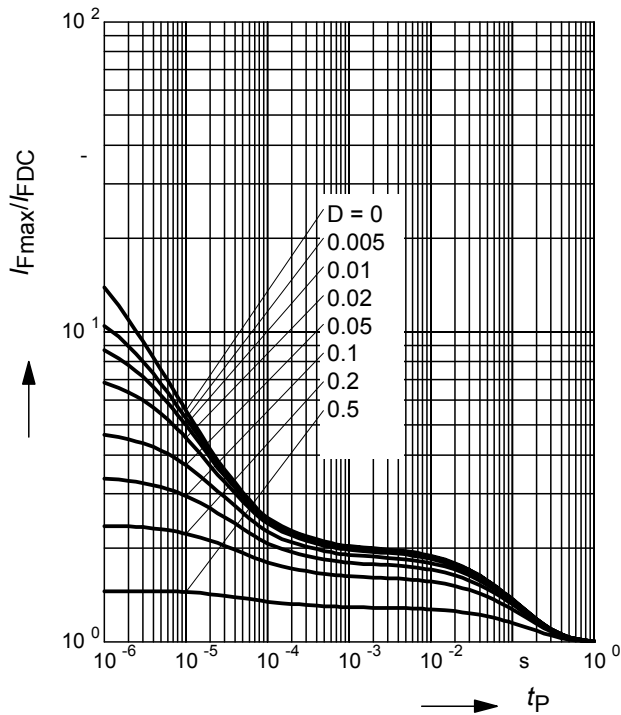
BAS70-04, BAS70-06



Permissible Pulse Load

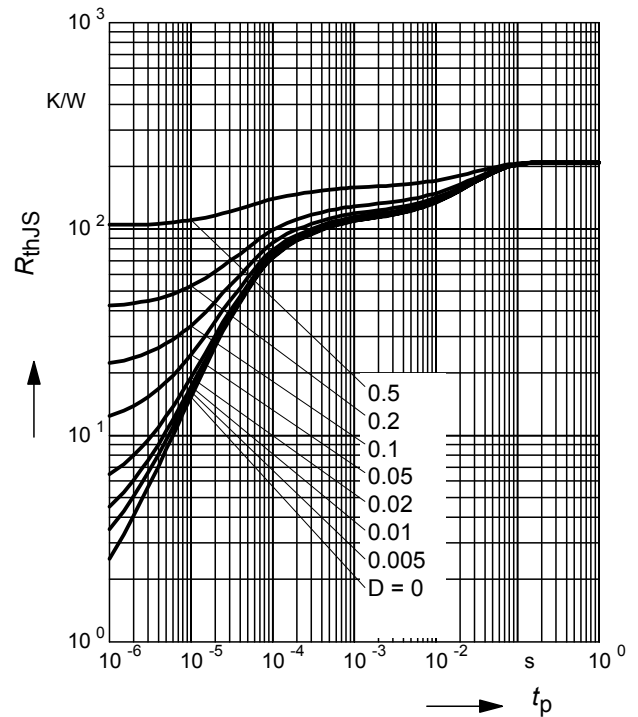
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAS70-04, BAS70-06



Permissible Puls Load $R_{thJS} = f(t_p)$

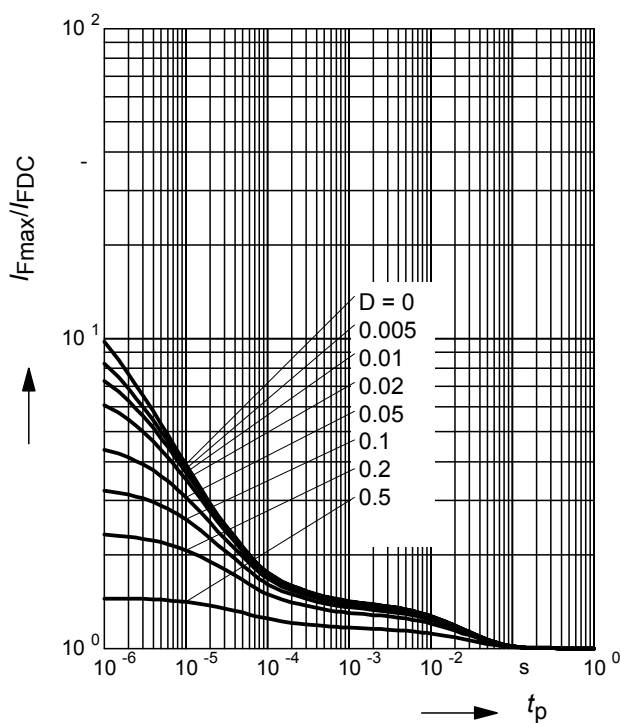
BAS70-04S



Permissible Pulse Load

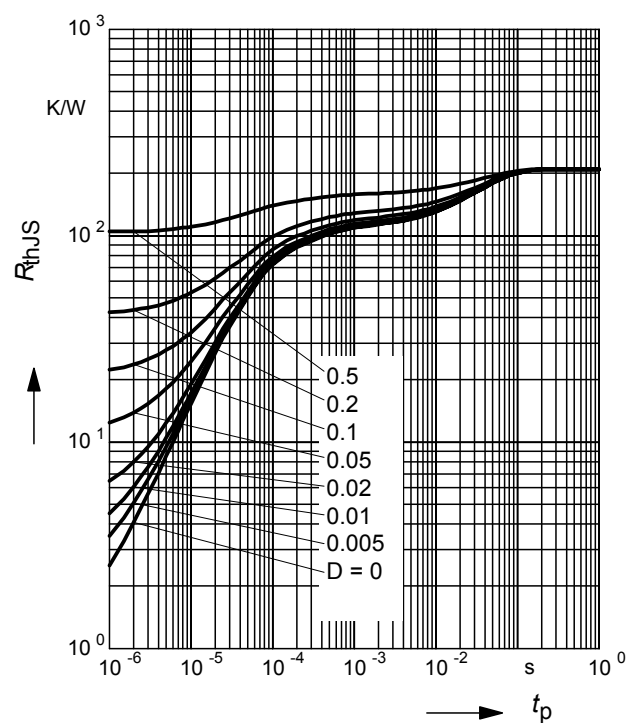
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAS70-04S



Permissible Puls Load $R_{thJS} = f(t_p)$

BAS70-04W, BAS70-06W



Permissible Pulse Load

$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAS70-04W, BAS70-06W



Permissible Puls Load $R_{thJS} = f(t_p)$

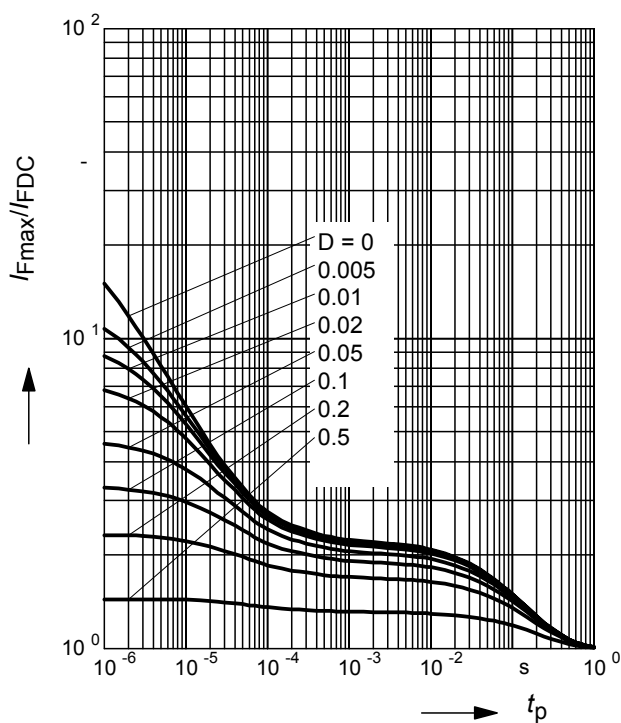
BAS70-05



Permissible Pulse Load

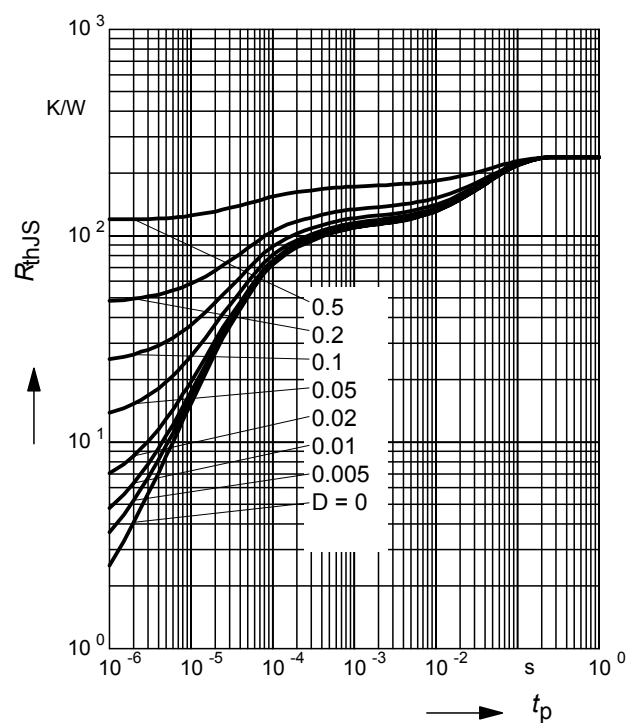
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAS70-05



Permissible Puls Load $R_{thJS} = f(t_p)$

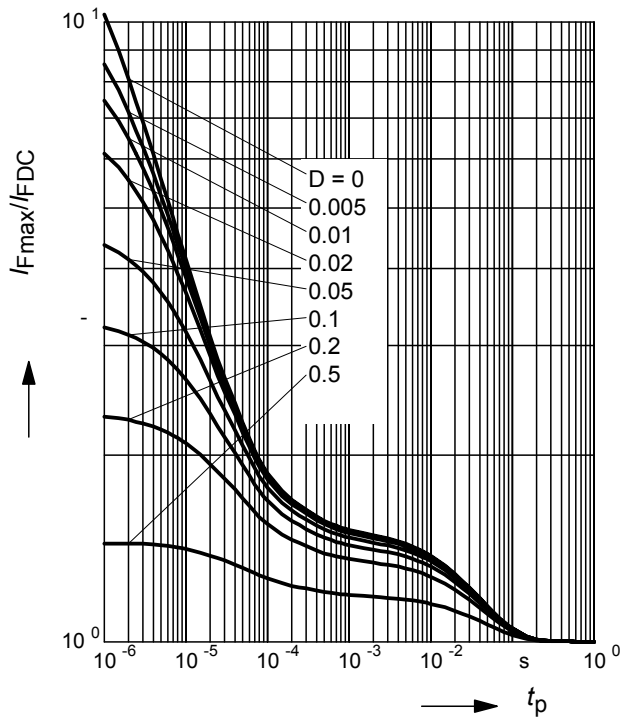
BAS70-05W



Permissible Pulse Load

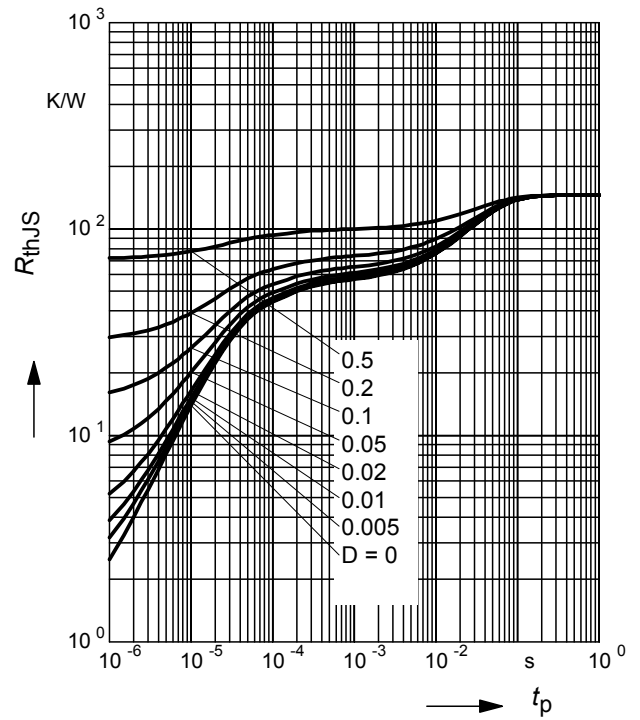
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAS70-05W



Permissible Puls Load $R_{thJS} = f(t_p)$

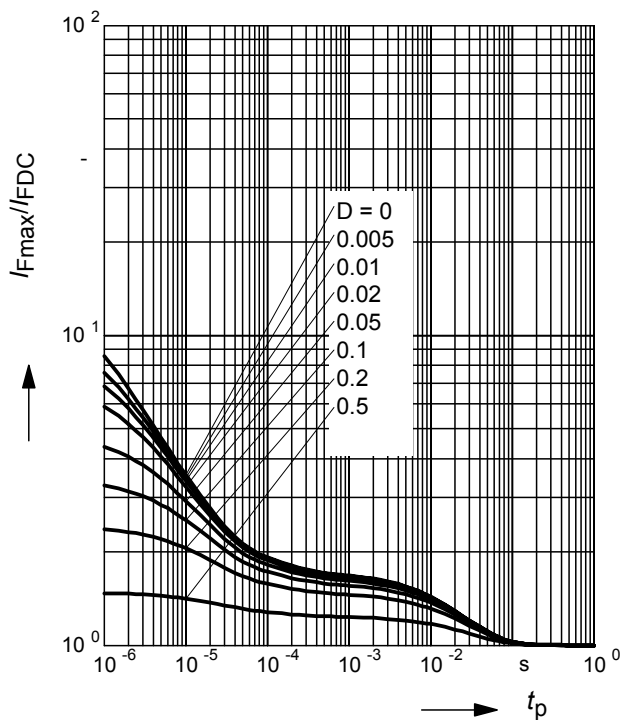
BAS70-07W



Permissible Pulse Load

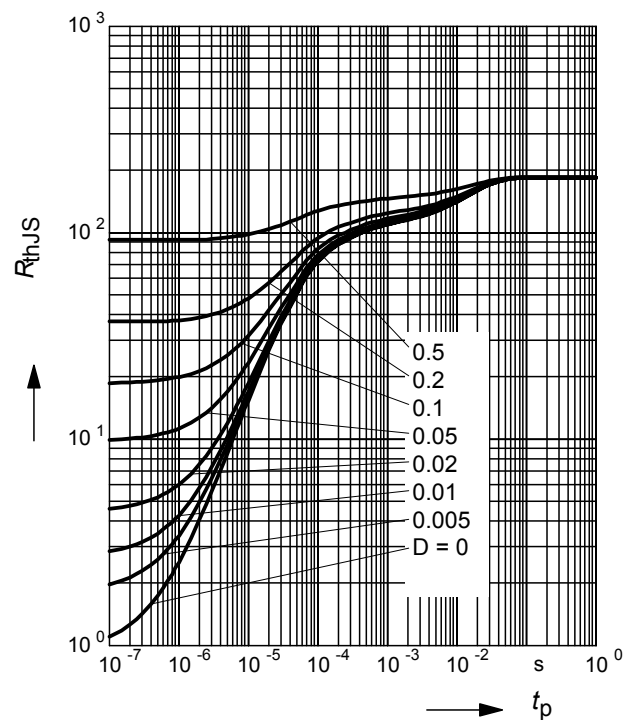
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAS70-07W



Permissible Puls Load $R_{thJS} = f(t_p)$

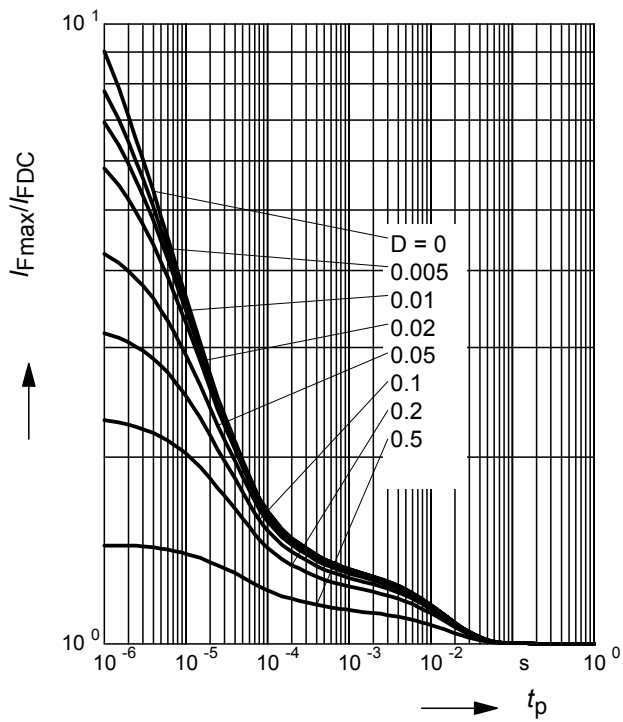
BAS170W



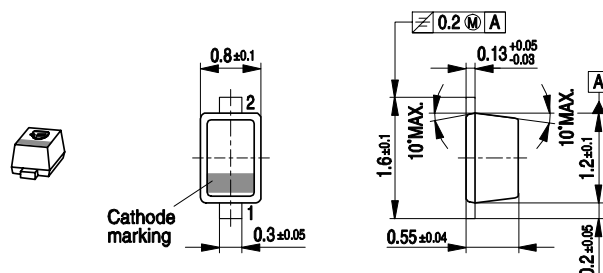
Permissible Pulse Load

$$I_{Fmax}/I_{FDC} = f(t_p)$$

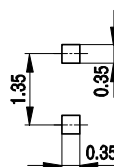
BAS170W



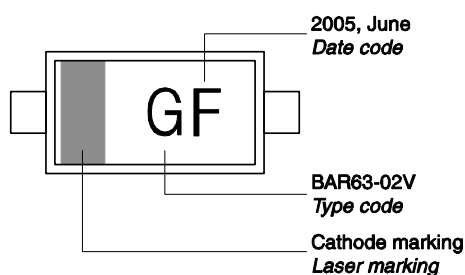
Package Outline



Foot Print

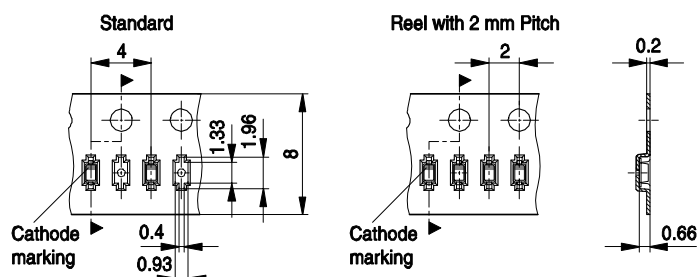


Marking Layout (Example)

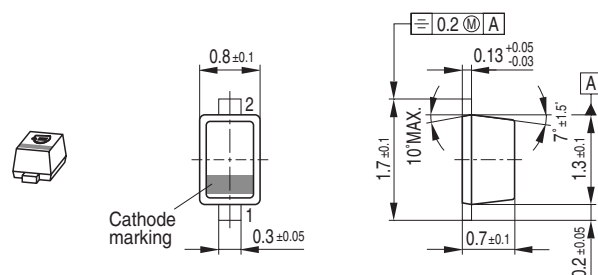


Standard Packing

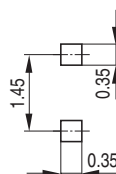
Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)
 Reel ø330 mm = 10.000 Pieces/Reel



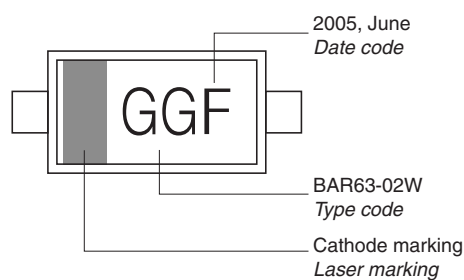
Package Outline



Foot Print

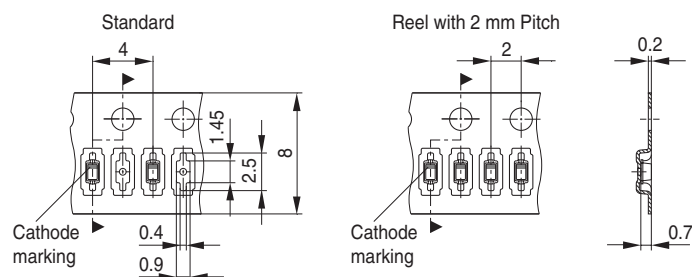


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)
 Reel ø330 mm = 10.000 Pieces/Reel

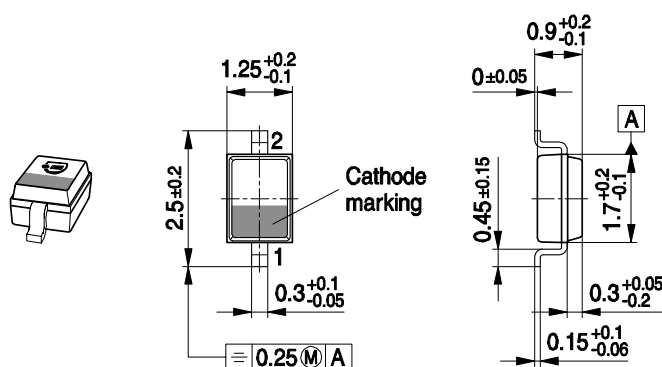


Date Code marking for discrete packages with one digit (SCD80, SC79, SC75¹⁾) CES-Code

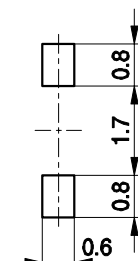
Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

1) New Marking Layout for SC75, implemented at October 2005.

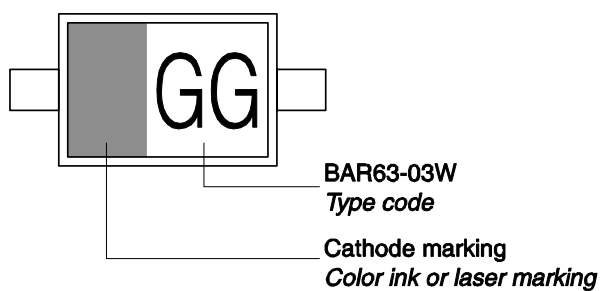
Package Outline



Foot Print

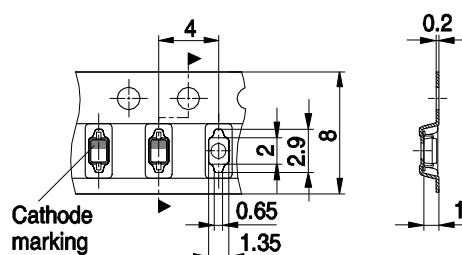


Marking Layout (Example)

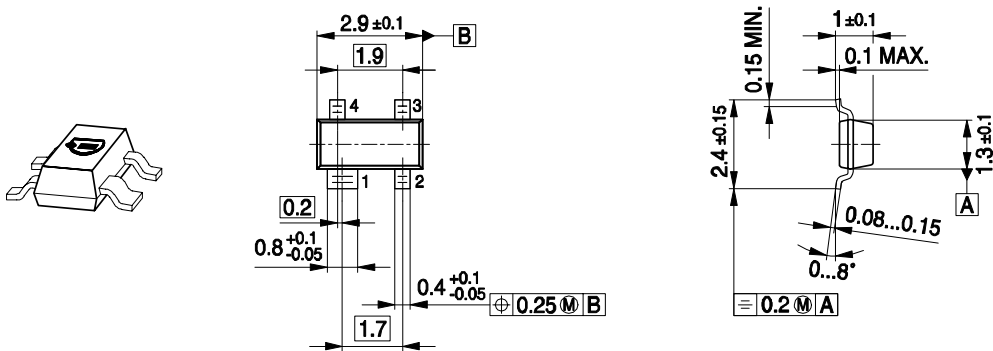


Standard Packing

Reel $\varnothing 180 \text{ mm}$ = 3.000 Pieces/Reel
 Reel $\varnothing 330 \text{ mm}$ = 10.000 Pieces/Reel



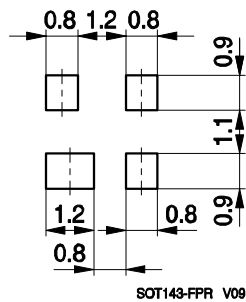
Package Outline



Note: Mold flash, protrusions or gate burrs of 0,2 mm max. per side are not included

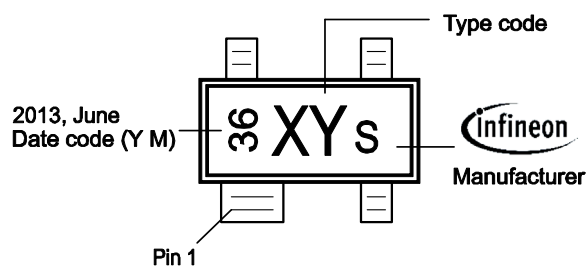
SOT143-PO V09

Foot Print



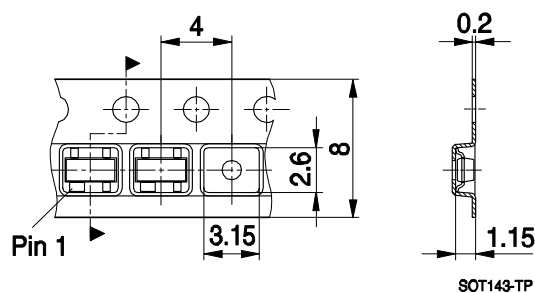
SOT143-FPR V09

Marking Layout (Example)



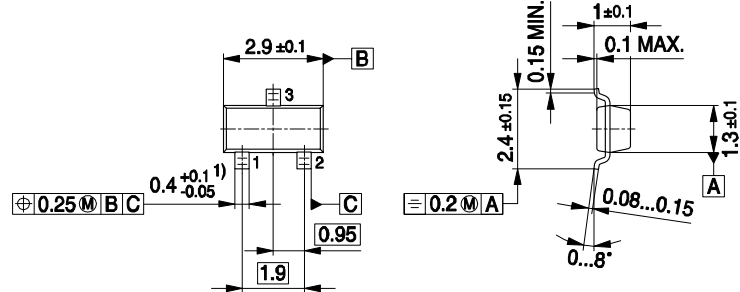
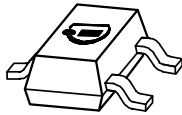
Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



SOT143-TP

Package Outline



1) Lead width can be 0.6 max. in dambar area

SOT23-PO V08

Foot Print



SOT23-FPR V08

Marking Layout



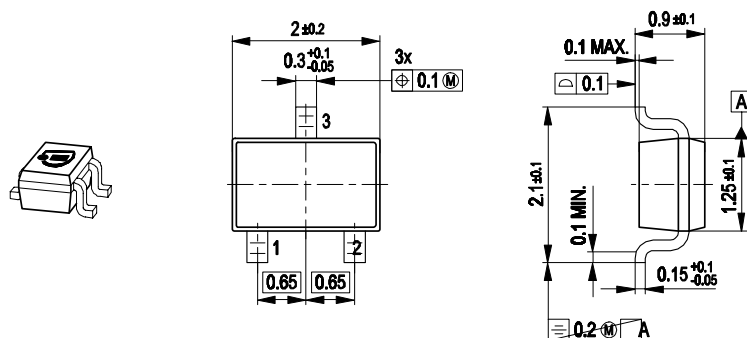
Standard Packing

Reel o 180 mm: 3.000 Pieces / Reel
Reel o 330 mm = 10.000 Pieces / Reel

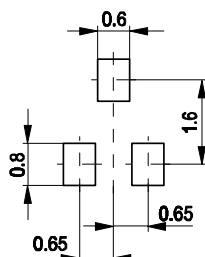


SOT23-TP V02

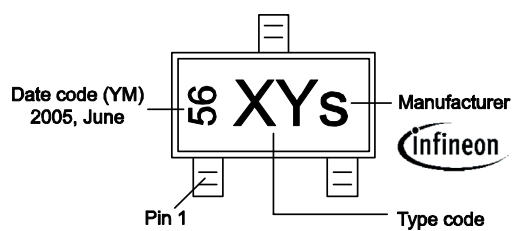
Package Outline



Foot Print

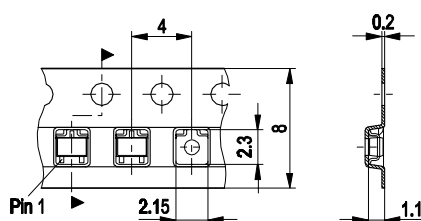


Marking Layout (Example)

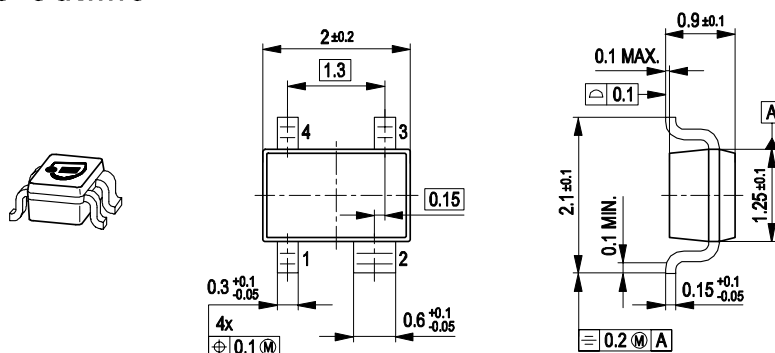


Standard Packing

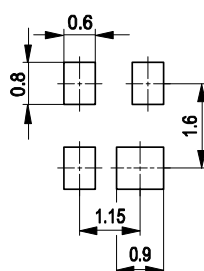
Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø330 mm = 10.000 Pieces/Reel



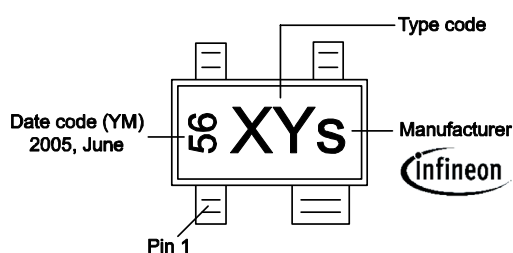
Package Outline



Foot Print

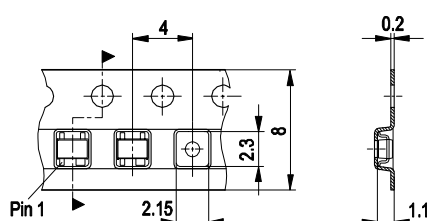


Marking Layout (Example)



Standard Packing

Reel $\varnothing 180 \text{ mm}$ = 3.000 Pieces/Reel
 Reel $\varnothing 330 \text{ mm}$ = 10.000 Pieces/Reel



The drawing shows the mechanical specifications for the 6-pin connector. The top view (left) shows a rectangular component with six pins. The overall width is 2 ± 0.2 mm. The distance between the centerlines of the pins is $0.2^{+0.1}_{-0.05}$ mm. The pin pitch is 0.65 mm. The pins are numbered 1 through 6, with Pin 1 marking indicated. The side view (right) shows the profile of the connector. The overall height is 0.9 ± 0.1 mm. The distance from the top surface to the top of the pins is 0.1 MAX. mm. The distance from the bottom surface to the bottom of the pins is 0.1 MIN. mm. The distance from the bottom surface to the top of the pins is 2.1 ± 0.1 mm. The distance from the bottom surface to the bottom of the pins is $0.15^{+0.1}_{-0.05}$ mm. The distance from the bottom surface to the top of the pins is 1.25 ± 0.1 mm. The drawing includes a 3D perspective view of the connector on the left.

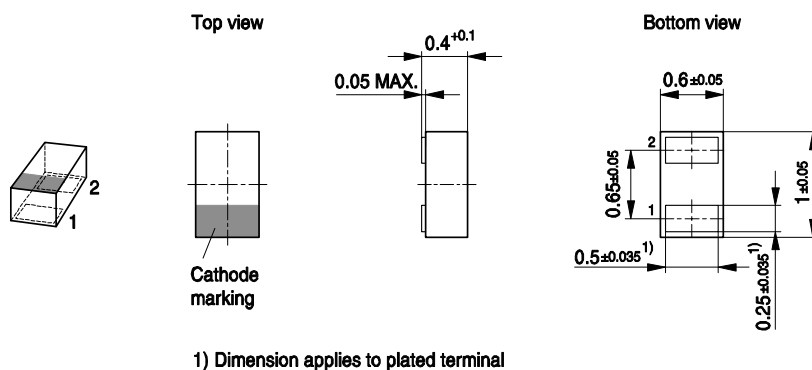
Technical drawing of a 2x2 grid of rectangular features. The drawing includes the following dimensions:

- Horizontal spacing between features: 0.3
- Vertical spacing between features: 0.7
- Feature width: 0.9
- Feature height: 1.6
- Horizontal offset from center: 0.65
- Vertical offset from center: 0.65

Diagram illustrating the marking on a 14-pin DIP package:

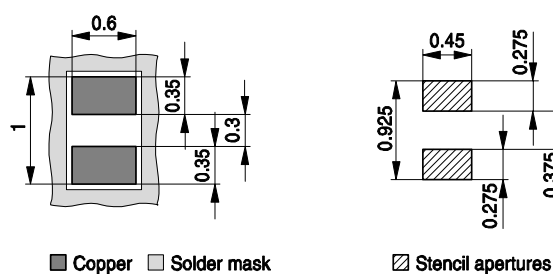
- Date code (YM)**: 2005, June
- Pin 1 marking**: Laser marking
- Markings**: 56, **XYS**
- Manufacturer**: Infineon
- Type code**: **XYS**

Package Outline

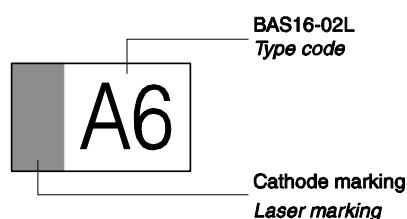


Foot Print

For board assembly information please refer to Infineon website "Packages"

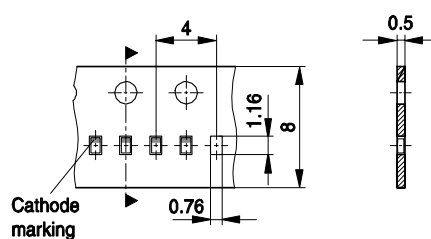


Marking Layout (Example)



Standard Packing

Reel $\varnothing$ 180 mm = 15.000 Pieces/Reel
Reel $\varnothing$ 330 mm = 50.000 Pieces/Reel (optional)



Edition 2009-11-16

**Published by
Infineon Technologies AG
81726 Munich, Germany**

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